

**N-Ch MOSFET** 

## **General Description**

The WSP14N10 is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSF14N10 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

### **Product Summery**

BVDSS	RDSON	ID
100V	16mΩ	14A

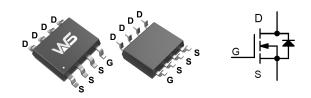
# **Applications**

Load switch

Battery protection

Uninterruptible power supply

## **SOP-8 Pin Configuration**



## **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units	
$V_{DS}$	Drain-Source Voltage	100	V	
$V_{GS}$	Gate-Source Voltage	±20	V	
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	14	А	
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	42	Α	
EAS	Single Pulse Avalanche Energy <sup>3</sup> L=0.1mH	30	mJ	
P <sub>D</sub> @T <sub>A</sub> =25℃	Total Power Dissipation⁴	72	W	
T <sub>STG</sub>	Storage Temperature Range -55 to 150		$^{\circ}$	
$T_J$	Operating Junction Temperature Range -55 to 1		$^{\circ}$	

### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>		40	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>		24	°C/W



# Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	100			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA		0.098		V/℃
В	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =8A		16	20	- mΩ
R <sub>DS(ON)</sub>		V <sub>GS</sub> =4.5V , I <sub>D</sub> =6A		25	28	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V -V 1 -250	1.0	1.5	2.5	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D=250uA$		-5.52		mV/℃
,	Drain Source Leakage Current	V <sub>DS</sub> =100V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃			1	uA
I <sub>DSS</sub>	Drain-Source Leakage Current  V <sub>DS</sub> =100V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C	V <sub>DS</sub> =100V , V <sub>GS</sub> =0V , T <sub>J</sub> =55℃			5	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm 20 V$ , $V_{DS}$ = $0 V$			±100	nA
$R_g$	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		0.55	1.0	Ω
Qg	Total Gate Charge (10V)			19.8		
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =50V , V <sub>GS</sub> =10V , I <sub>D</sub> =8A		2.4		nC
Q <sub>gd</sub>	Gate-Drain Charge			5.3		
T <sub>d(on)</sub>	Turn-On Delay Time			17.8		
Tr	Rise Time	V <sub>DD</sub> =50V , V <sub>GS</sub> =10V ,		3.9		
T <sub>d(off)</sub>	Turn-Off Delay Time	R <sub>G</sub> =2.2Ω I <sub>D</sub> =10A		33.5		ns
T <sub>f</sub>	Fall Time			3.2		
C <sub>iss</sub>	Input Capacitance			1191		
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =50V , V <sub>GS</sub> =0V , f=1MHz		195		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			41		

### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			40	Α
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =8A , T <sub>J</sub> =25℃			1.3	V
t <sub>rr</sub>	Reverse Recovery Time			50		nS
Q <sub>rr</sub>	Reverse Recovery Charge	∏F=8A , dl/dt=100A/μs , T J=25℃		95		nC

### Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_a$ =25 °C.
- 5)  $V_{DD}$ =50 V,  $R_G$ =25  $\Omega$ , L=0.3 mH, starting  $T_j$ =25  $^{\circ}$ C.



### TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

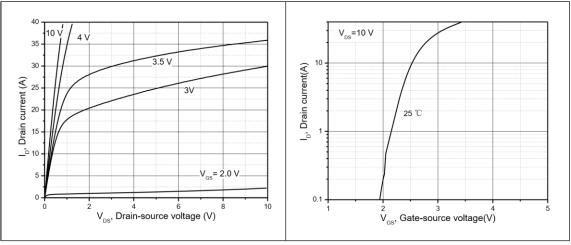


Figure 1, Typ. output characteristics

Figure 2, Typ. transfer characteristics

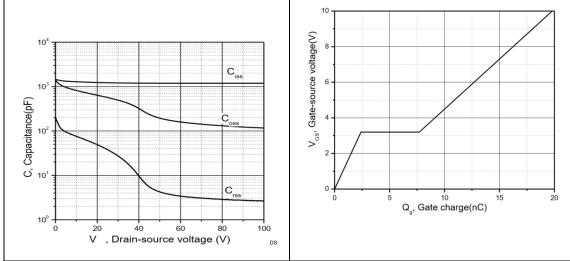


Figure 3, Typ. capacitances

Figure 4, Typ. gate charge

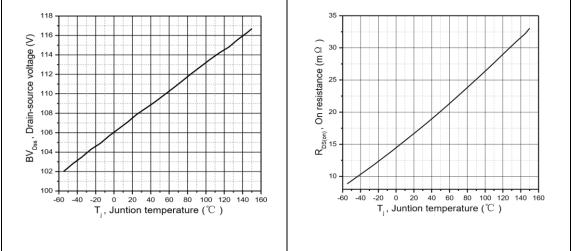
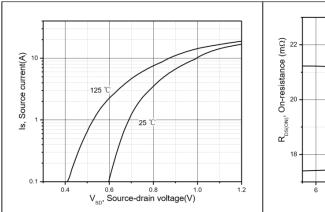


Figure 5, Drain-source breakdown voltage

Figure 6, Drain-source on-state resistance



## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



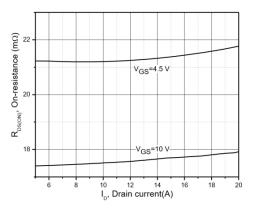


Figure 7, Forward characteristic of body diode

Figure 8, Drain-source on-state resistance

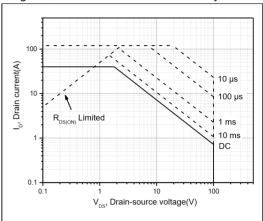


Figure 9, Safe operation area  $T_C=25\,^{\circ}C$ 



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